

PD 977

SMT-Adhesive

Low Temperature Fast Curing SMT-Adhesive

Description

PD 977 is a thermosetting single-component, solvent-free polymer adhesive, developed for the surface mounting of SMT components on to PCBs and bare substrates.

PD 977 has been optimised for low temperature (< 100 °C) curing properties.

The rheology of this glue is adapted for high-speed-dispensing. It allows for very low Z-Height-returns - the height above the board that the dispense head will retract to upon completion of the dispense cycle.

Special advantages

- Very wide processing window, no tendency to string.
- Specially developed for high-speed dispensing.
- Dispensing with very low Z-Height-return possible.

Physical characteristics

Colour:	red
Homogeneity:	no particles >50 µm
Adhesion:	≥ 25 N/mm ² at room temperature.

Processing

The adhesive is suitable for machine and manual dispensing.
Stencil printing is possible.

Curing

The standard curing conditions are: **90 °C (195 °F) / 3'**.
Max. curing temperature should not be higher than 125 °C (255 °F). The minimum* curing times in tunnel type oven are shown in the following list.

80 °C (175 °F)	90 °C (195 °F)
5 '	3 '

Graphic Curing Time; page 2

* Optimal curing conditions depend on the oven.

Cleaning

Before curing:

The uncured adhesive can be removed with alcohol or water based cleaning materials. Please contact your local representative for specific recommendations.

The cleaned parts must be completely dry before installing them in the machine.

After curing:

Because of the known residual thermoplasticity of the cured adhesive, defective components can be easily replaced by heating (with hot air) the cured adhesive joint above 100 °C. After removing the component (torsion movement), the hot air should be focused on the remaining adhesive in order to remove it with a sharp tool.

Packing

The adhesives PD 977 can be filled in various machine-specified syringes.

Storage

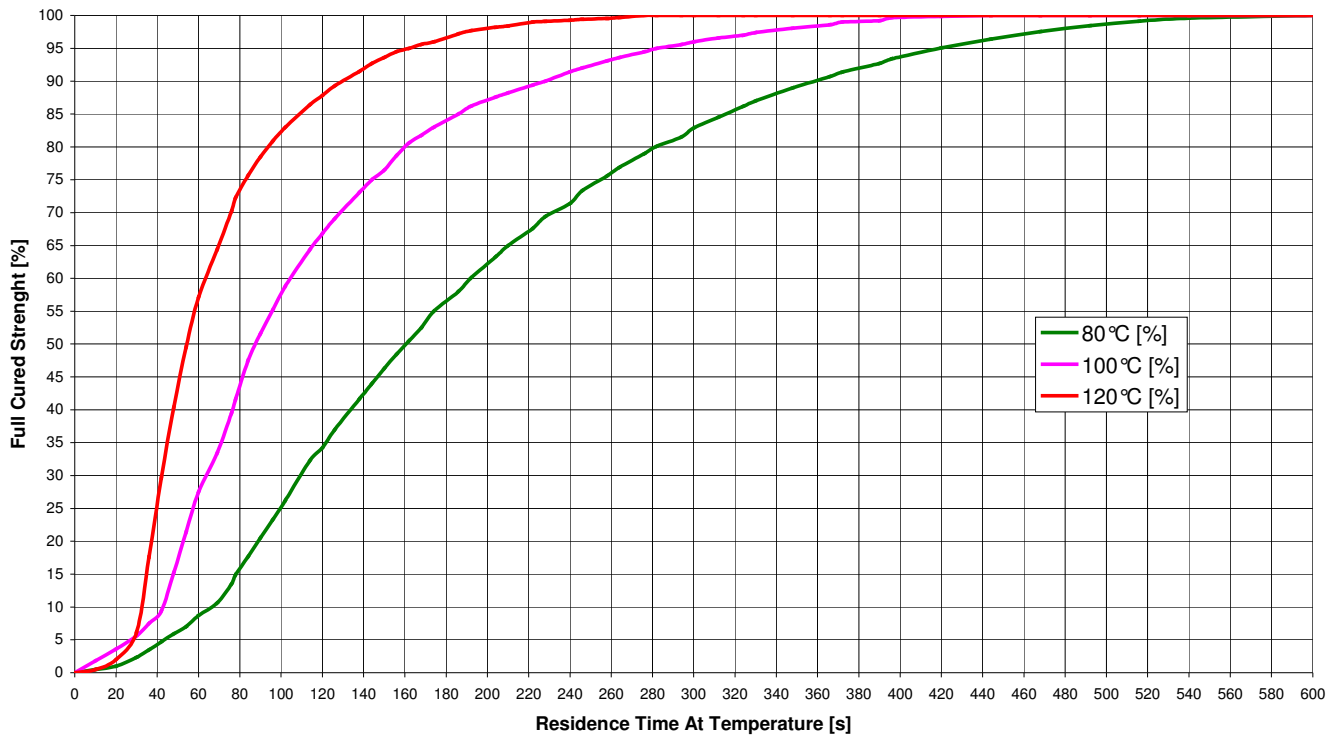
Storage time:

6 months in a refrigerator, at a storage temperature of 5 - 12 °C (40 - 54 °F).

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Curing Time PD 977



Adhesion is high enough at 85 % full cured strength.

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